

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|---------------------|
| L30 | 0 | method attaching semiconductor assembly comprising device active surface first end second lateral side substrate upper wall applying silane- based material layer one portion connecting faces flowable underfill between contacts | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/01/29 19:15 |

1/ 29/ 2009 7:15:28 PM

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